

ABSTRACT OF THE DISCLOSURE

A method of manufacturing an electromagnetic interference shield (3) includes the steps of: preparing a substrate (30) and at least one target module (1), and mounting them in a sputtering chamber (100), wherein each target module has a target (10) bonded thereto, and the target is made from an electrically conductive material; evacuating the sputtering chamber to a predetermined degree of vacuum; introducing a working gas into the sputtering chamber to a predetermined gas pressure level; applying a voltage to the target module using a power supply (2), thus activating a magnetron sputtering process between the target module and the substrate, and depositing at least one electrically conductive layer (31) from the target module onto the substrate until a desired thickness is achieved on the substrate.